Gallium Nitride 28V 70W, C band RF Power Transistor

Description

The GTAH58070L4 is a 70W internally matched, GaN HEMT, designed from 5GHz to 6GHz, especially 5G NR or LTE application, as well as either Pulse or CW application There is no guarantee of performance when this part is used in applications designed Outside of these frequencies.



Typical CW performance (on 5.7-5.9GHz fixture with device soldered):

GTAH58070L4V0 Vgs=-2.59V Vds=28V Idq=40mA CW						
Freq (MHz)	Psat (dBm)	Psat (W)	lds (A)	Pin (dBm)	Gain (dB)	Eff (%)
5700	48.87	77.1	4.99	36.02	12.85	55.17
5750	48.85	76.7	4.86	35.48	13.37	56.39
5800	48.66	73.5	4.70	35.40	13.26	55.81
5850	48.67	73.6	4.60	35.68	12.99	57.16
5900	48.60	72.4	4.58	35.80	12.80	56.49

Applications and Features

- Suitable for wireless communication infrastructure, wideband amplifier, EMC testing, ISM etc.
- High Efficiency and Linear Gain Operations
- Thermally Enhanced Industry Standard Package
- High Reliability Metallization Process

2. Reduce VGS down to VP, typically -5 V

- Excellent thermal Stability and Excellent Ruggedness
- Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC

Important Note: Proper Biasing Sequence for GaN HEMT Transistors

Turning the device ON

- 1. Set VGS to the pinch--off (VP) voltage, typically –5 V $\,$
- 2. Turn on VDS to nominal supply voltage (28V)
- 3. Increase VGS until IDS current is attained
- 4. Apply RF input power to desired level

Figure 1: Pin Connection definition

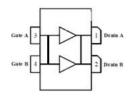
4. Turn off VGS

1. Turn RF power off

Turning the device OFF

3. Reduce VDS down to 0 V

Transparent top view (Backside grounding for source)



*Notice: Both leads at input and output are internally connected, device is only usable as single ended

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	150	Vdc
GateSource Voltage	V _{GS}	-10,+2	Vdc
Operating Voltage	V _{DD}	36	Vdc
Maximum Forward Gate Current @ Tc = 25°C	Igmax	18	mA
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature(See note 1)	TJ	+225	°C
Total Device Power Dissipation (Derated above 25°C, see note 2)	Pdiss	120	w

 Note:
 1. Continuous operation at maximum junction temperature will affect MTTF

 2.Bias Conditions should also satisfy the following expression: Pdiss < (Tj – Tc) / RJC and Tc = Tcase</td>

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case	Rejc	1	C/W
T _c = 85°C, RF CW operation, Pout=70W, 5.8GHz	Kelc	1	C/ VV

Table 3. Electrical Characteristics (T_c = 25°C unless otherwise noted)

DC Characteristics

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	V _{GS} =-8V; I _{DS} =18mA	V _{DSS}	150			V
Gate Threshold Voltage	V _{DS} = 28V, I _D =18mA	V _{GS} (th)	-4		-2	V
Gate Quiescent Voltage	V _{DS} =28V, I _{DS} =40mA, Measured in Functional Test	V _{GS(Q)}		-2.6		v

Typical performance

5.7-5.9GHz

Figure 1: Small singal gain and return loss Vs Frequency Vgs=-2.5V, Vds=28V, Idq=100mA, input power=0dBm

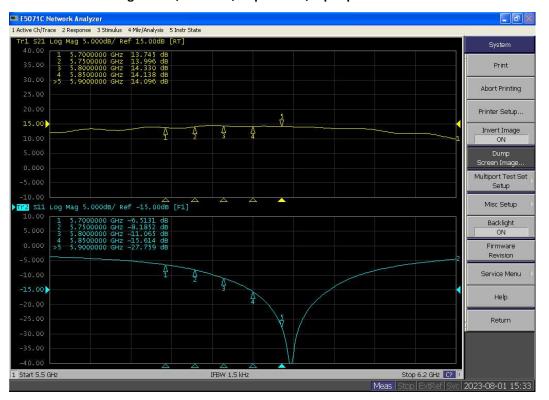
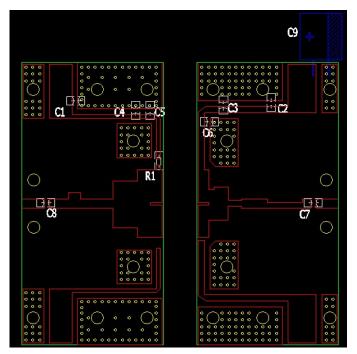
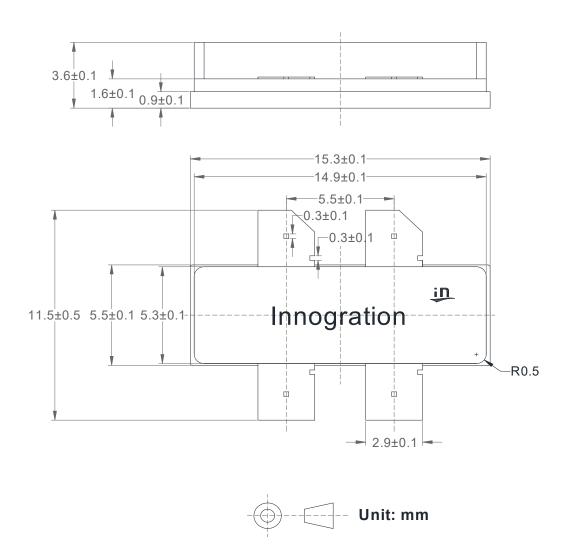


Figure 3: Picture and Bill of materials of 5.7-5.9GHz wide band application circuit (Layout Gerber file upon request)



Component	Description	Suggestion
C1,C2	10uF	10uF/100V
C3	6.2pF	MQ101111
C4	6.8pF	MQ101111
C5,C6	3pF	MQ101111
C7	3pF	0805
C8	4.7pF	0805
C9	470uF/63V	Electrolytic Capacitor
R1	10 Ω	Chip Resistor
PCB	30Mil	Rogers4350

Earless Flanged Ceramic Package; 4 leads



Revision history

Table 4. Document revision history

Date	Revision	Datasheet Status
2023/8/2	V1.0	Production Datasheet Creation

Application data based on TC-23-48

Notice

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